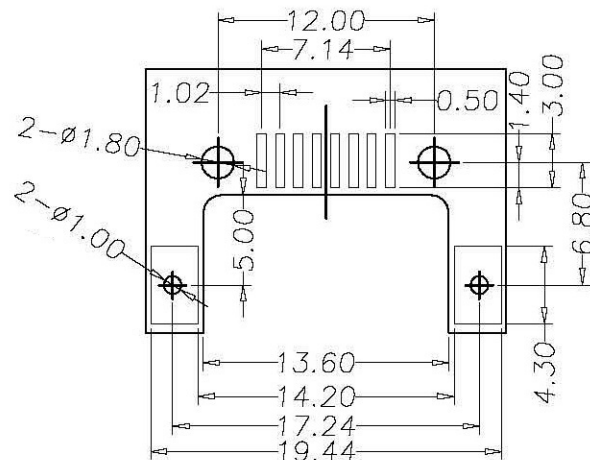
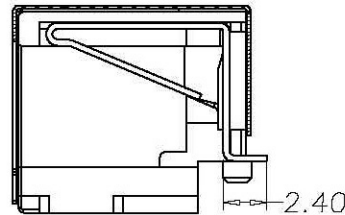
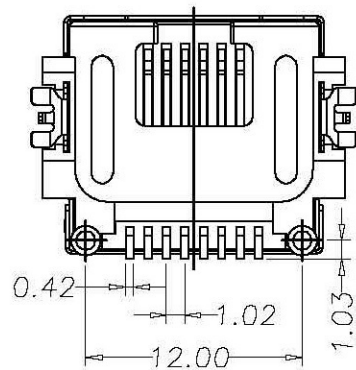
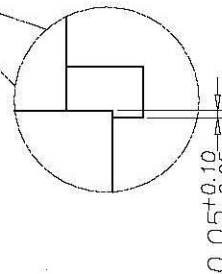
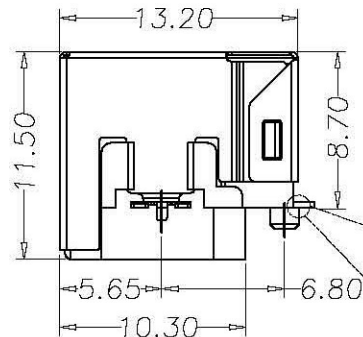
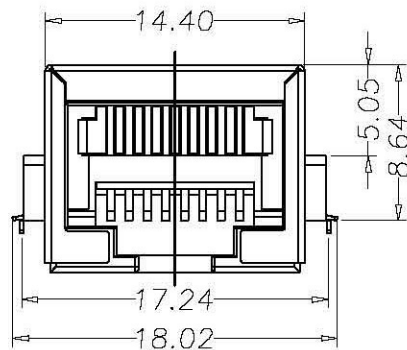




PC Board Layout

增加料号选项 xushiyang 09.04.20

REVISION RECORD

REV	ECO	DESCRIPTION	DRFT	CHKD
△		原始版本		
△		增加料号,更改图号		

NOTES:

MATERIAL:

- 1.HOUSING MATERIAL :GLASS FILLED POLYESTER(UL94V-0).
- 2.CONTACT MATERIAL :PHOSPHOR BRONZE T=0.35mm (C5100).
- 3.PLATING :GOLD PLATING OVER NICKEL.
- 4.SHIELD: COPPER ALLOY 0.20mm THICKNESS PLATING NI.

ELECTRICAL:

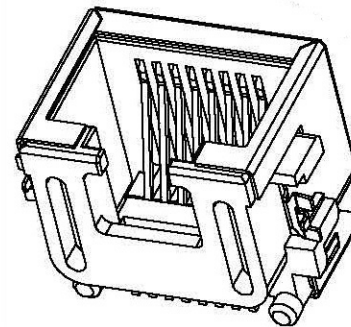
- 1.VOLTAGE RATING :125 VAC RMS.
- 2.CURRENT RATING :1.5 AMP.
- 3.CONTACT RESISTANCE :50 MILLIOHMS MAX.
- 4.INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC.
- 5.DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

- 1.DURRABILITY :750 CYCLES MIN.
- 2.PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

- 1.STORAGE : -40°C TO +85°C.
 2. OPERATION : -20°C TO 70°C.
- MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68,SUBPART F.



DETACHED LISTS	MM (INCH)		设计 ZHANGWUJ	日期 13.03.10	深圳市连欣科技有限公司	
	一般公差		审核	日期		
	MM		批准 zhangke	日期 13.03.10	系列	名称
	.0 ± 0.20	±	材料: 材料		系列	RJ45 卧式沉板式8.7MM SMT
	.00 ± 0.15	±	数量: 数量		料号: XDRJ-0303-087	A3 版本
角度 ± 0.01°			表面处理: 表面处理		图号: DWG03*087	共 X 页 第 Y 页
第三角视图			比例: 比例			